

## **Vanguard International Semiconductor Summary**

· Plant Address

123, Park Ave-3rd, Science-Based Industrial Park, Hsinchu, Taiwan 30077, R.O.C.

Headcount

5,200

· Total Building size in sq. ft. and fab size in sq. meters

880,543.3 sq. feet (Building 1)

· Clean room floor space in sq. meters

12,600 sq. meters (Building 1)

· Fab utilization in percent

Fab 1: 100%

· Land Area in sq. meters

41,925 sq. meters

· Wafer capacity for each facility

Fab 1: 87K wafers per month (ADI's material is scheduled to run in Fab 1)

- A list of certifications (i.e. TS16949, ISO-14001, etc.)
  - ISO 9001 Quality Management System (since 1996)
  - ISO 14001 Environment Management System (since 1997)
  - OHSAS 18001 Health & Safety Management System (since 2003)
  - QC 080000 Hazardous Substance Management System (since 2007)
  - ISO 27001 Information Security Management System (since 2015)
  - IATF 16949 Automotive Quality Management System (since 2018)

## Qualification Summary of 3104 Die at Vanguard for LTM4700, LTM4681, LTM4636

LTC3104 at Vanguard Qualification Results			
Test	Specification	Sample Size (lots x samples)	Results
Temperature Cycle (TC)*	JEDEC JESD22-A104	3 x 77	Pass
Unbiased Highly Accelerated Stress Test (UHAST)*	JEDEC JESD22-A118	3 x 77	Pass
High Temperature Storage (HTSL)	JEDEC JESD22-A103	3 x 45	Pass
High Temperature Operating Life (HTOL)	JEDEC JESD22-A108	3 x 77	Pass
Early Life Failure Rate (ELFR)	AEC-Q100-008	3 x 800	Pass
Highly Accelerated Stress Test (HAST)*	JEDEC JESD22-A110	3 x 77	Pass

<sup>\*</sup> Tests were preceded by MSL 1 Preconditioning: 24h 125C bake, 168h 85C/85% unbiased soak, and 3 reflow passes at 260°C peak.